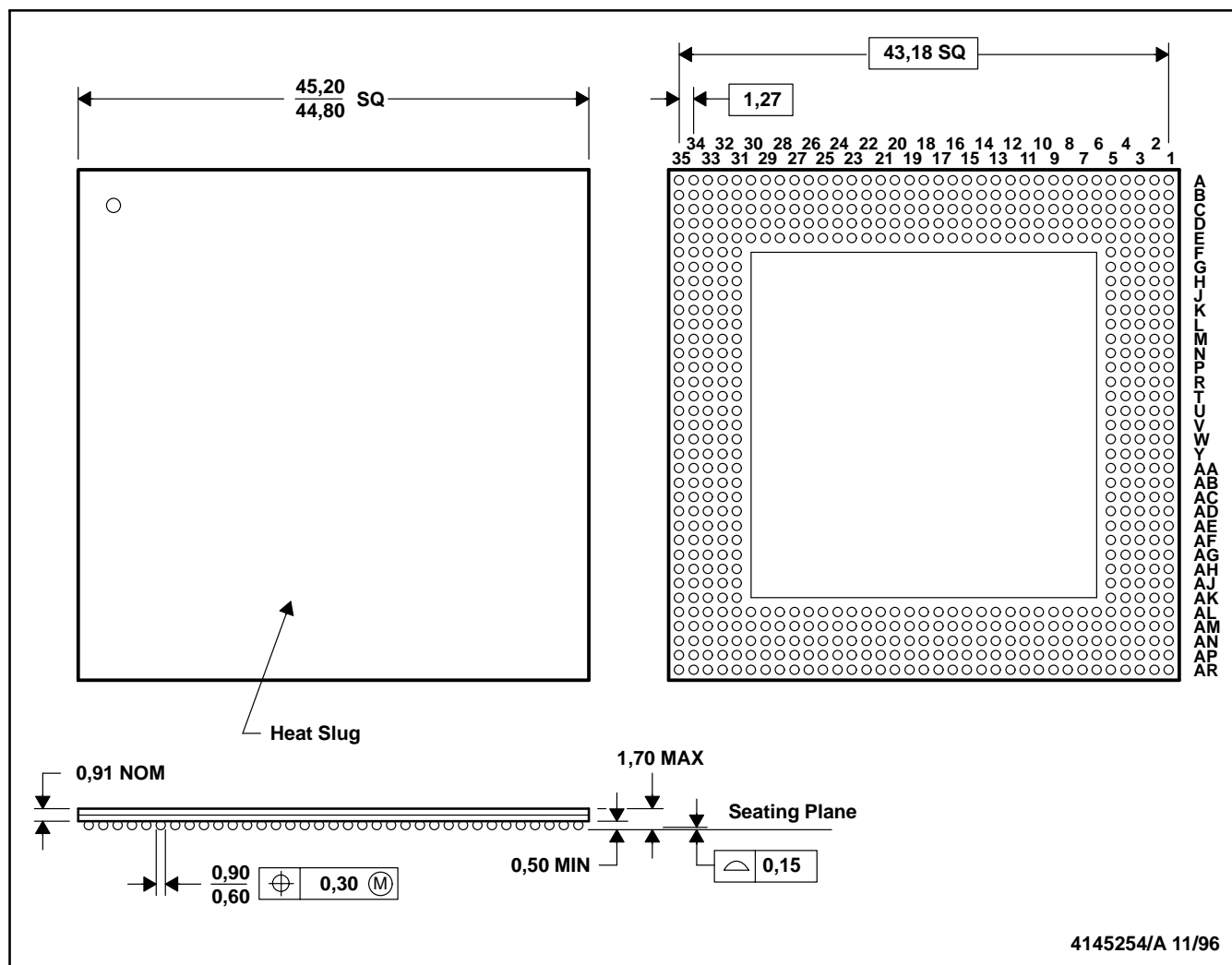


GGS (S-PBGA-N600)

PLASTIC BALL GRID ARRAY (CAVITY-DOWN) PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Thermally enhanced die down plastic package with top surface metal heat slug.

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